

RELIABILITY REPORT
FOR
MAX7301AAI+
PLASTIC ENCAPSULATED DEVICES

January 27, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
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Approved by
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Conclusion

The MAX7301AAI+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX7301 compact, serial-interfaced I/O expander (or general-purpose I/O (GPIO) peripheral) provides microprocessors with up to 28 ports. Each port is individually user configurable to either a logic input or logic output. Each port can be configured either as a push-pull logic output capable of sinking 10mA and sourcing 4.5mA, or a Schmitt logic input with optional internal pullup. Seven ports feature configurable transition detection logic, which generates an interrupt upon change of port logic level. The MAX7301 is controlled through an SPI(tm)-compatible 4-wire serial interface. The MAX7301AAX and MAX7301ATL have 28 ports and are available in 36-pin SSOP and 40-pin TQFN packages, respectively. The MAX7301AAI has 20 ports and is available in a 28-pin SSOP package. For a 2-wire I²C-interfaced version, refer to the MAX7300 data sheet. For a pin-compatible port expander with additional 24mA constant-current LED drive capability, refer to the MAX6957 data sheet.

II. Manufacturing Information

A. Description/Function:	4-Wire-Interfaced, 2.5V to 5.5V, 20-Port and 28-Port I/O Expander
B. Process:	5um, 2 Poly 3 Metal CMOS
C. Number of Device Transistors:	
D. Fabrication Location:	Taiwan
E. Assembly Location:	Unisem Malaysia, ATP Philippines, Carsem Malaysia
F. Date of Initial Production:	April 27, 2002

III. Packaging Information

A. Package Type:	28-pin SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3301-0017
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	25°C/W
L. Multi Layer Theta Ja:	67.1°C/W
M. Multi Layer Theta Jc:	25°C/W

IV. Die Information

A. Dimensions:	122 X 104 mils
B. Passivation:	SiO ₂ (Oxide)/Si ₃ N ₄ (Nitride)
C. Interconnect:	Al/Cu (0.5%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.5um
F. Minimum Metal Spacing:	0.5um
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	Silicon dioxide
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 45 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 23.9 \times 10^{-9}$$

$$\lambda = 23.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the TSMC 0.5um Process results in a FIT Rate of 4.5 @ 25C and 77.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DW43 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX7301AAI+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data